

Title (en)

PROCESS AND APPARATUS FOR REGENERATING AN ELECTROLESS COPPER-PLATING BATH

Publication

EP 0240589 B1 19900207 (DE)

Application

EP 86105002 A 19860411

Priority

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Abstract (en)

[origin: US4734175A] A process and an apparatus are described for regenerating an electroless copper plating bath containing a complexing agent, preferably ethylenediamine tetraacetic acid. From the bath solution to be regenerated, the copper content is reduced by electrolysis to a value below 20 mg/l and the complexing agent subsequently precipitated by acidification and recovered. After dissolution in an alkaline electrolytic solution, the solution thus obtained is fed back to the electroless copper plating bath. A particularly pure ethylenediamine tetraacetic acid free from by-products is obtained if the pH value is kept constant during electrolysis, an anodic current density i_+ of 100 A/m² is not exceeded, and the anodic current density during electrolysis is reduced according to the electrolysis characteristic or in steps.

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